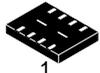


# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

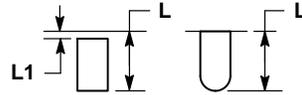
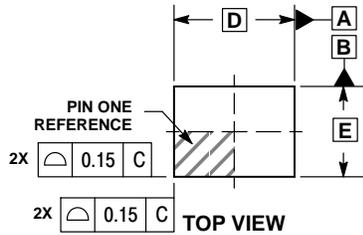
ON Semiconductor®



SCALE 2:1

UDFN8, 4x3, 0.8P  
CASE 506DC  
ISSUE O

DATE 05 FEB 2015

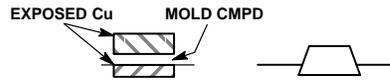
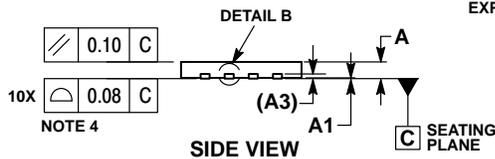


DETAIL A  
ALTERNATE TERMINAL  
CONSTRUCTIONS

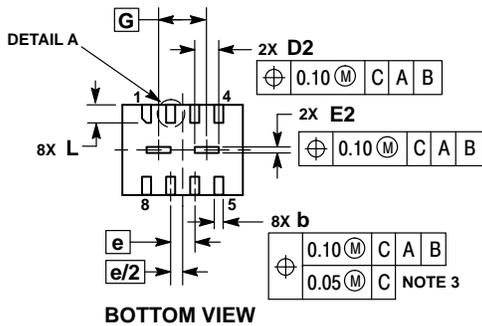
NOTES:

- DIMENSIONS AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETERS.
- DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30MM FROM THE TERMINAL TIP.
- COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

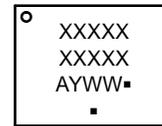
MILLIMETERS		
DIM	MIN	MAX
A	0.50	0.60
A1	0.00	0.05
A3	0.152	REF
b	0.25	0.35
D	4.00	BSC
D2	0.70	0.90
E	3.00	BSC
E2	0.10	0.30
e	0.80	BSC
G	1.60	BSC
L	0.55	0.65
L1	---	0.15



DETAIL B  
ALTERNATE  
CONSTRUCTIONS



GENERIC  
MARKING DIAGRAM\*

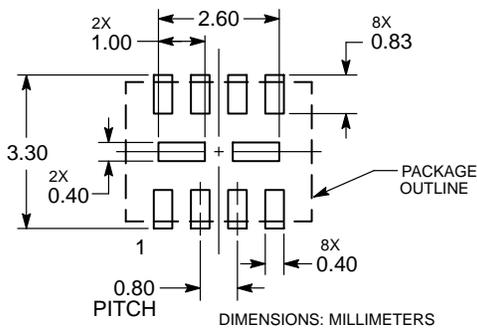


- XXXXX = Specific Device Code
- A = Assembly Location
- Y = Year
- WW = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

RECOMMENDED  
SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	UDFN8, 4X3, 0.8P	PAGE 1 OF 2

